APSEMI

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1 Form A APY212G1E_EH SMD-4 Load Voltage:60V Load Current:1.1A

arameter	Symbol	Rating	Units			(U) E5347
oad Voltage	VL	60	V	Complaint lead-free	*746 PB0116C	20011
oad Current	١L	1.1	A			
n-Resistance	Ron	0.27	Ω	195	West	G. APY
O Breakdown Voltage	V/ıo	5000	Vrms			11-
	→ IL VL (AC,DC) →	(*) Input 1 (-) Input 2				
			ED Anode		DIP-4	SMD-4
	AC/DC	2. LI	ED Cathode			
		3.4. D	Drain(MOS FET)			

APSEMI PhotoRelays

APSEMI Photorelays are the most reliable, technically advanced logic-to-power interface devices. Their basic function is to take a low current signal from a microprocessor to control the switching of both AC and DC loads, while providing an isolation barrier between logic and power. While this function is common to all relays, Photorelays provide distinct advantages over their mechanical counterparts including:

- Long life (No limit on mechanical and electrical
- lifetime)Bounce-free switching
- Higher speed and high frequency switching
- Higher sensitivity (less power consumption)
- Immunity to EMI or RFI

- No have voltaic arc, bounce, and noise More
- resistant to vibration and impact AC or DC load
- switching
 - Small package size

Function

APSEMI PhotoRelays operate by taking a low level input current (<5mA) that energizes an input Infrared LED, which is optically-coupled to a Photo-diode array chip. This IC in turn generates a photo voltage that powers two MOSFETs typically connected in a source-to-source con! guration, allowing for both AC and DC output loads. Photorelay basically move photons to accomplish their switching function, they incur no mechanical wear and tear, providing consistent reliable switching.

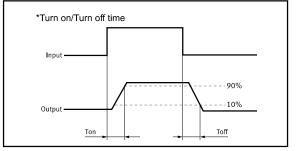
Applications

These advantages make APSEI Photorelays the ideal choice for:

- Telecom/Datacom switching
- Multiplexers
- Meter reading systems
- Data acquisition
- Medical equipment
- Battery monitoring
- I/O Sub-Systems

TPYES

	Category Load voltage Load current Package				Packing quantity	
Category			Package	Part No.		
		DIP4	APY212G1E	50pcs/tube		
AC/DC 60V	1.1A SMD4		APY212G1EH	1000pcs/1reel		



- Robotics Aerospace
- Home/Safety security systems
- Process Control
- Energy Management
- Reed Relay EMR Replacement
- Programmable Controllers



Absolute Maximum Ratings (Ta = 25°C)

	Item	Symbol	Value	Units	Note
Continuous LED Current		lF	50	mA	
Input	Peak LED Current	IFP	1000	mA	f=100Hz, duty=1%
	LED Reverse Voltage	VR	5	V	
	Input Power Dissipation	Pln	75	mW	
	Load Voltage	VL	60	V(AC peak or DC)	
Output	Load Current	l.	1.1	A	
	Peak Load Current	Peak	3.0	А	100ms(1 pulse)
	Output Power Dissipation	Pout	380	mW	
Total Pow	er Dissipation	Рт	450	mW	
I/O Breakdown Voltage		Vi/o	5000	Vrms	RH=60%, 1min
Operating Temperature		Topr	-40 to +85	°C	
Storage Temperature		Tstg	-40 to +100	°C	
Pin Soldering Temperature		T _{sol}	260	°C	10 sec max.

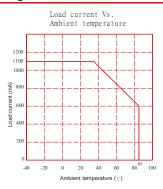
Electrical Specifications (Ambient Temperature: 25°C)

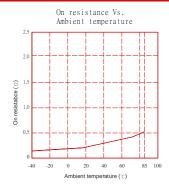
	ltem		MIN.	TYP.	MAX.	Units	Conditions
	LED Forward Voltage	VF		1.2	1.4	V	I⊧=10mA
Input	Operation LED Current	F on		0.5	5.0	mA	
	Recovery LED Current	F off		0.35	0.5	mA	
	Recovery LED Voltage	VF off	0.7			V	
	On-Resistance	Ron		0.27	0.7	Ω	I⊧=5mA,I∟=100mA, Time to flow is within 1 sec.
Output							
	Off-State Leakage Current	I _{Leak}	0.01	0.03	0.10	uA	V₋=Rating
	Output Capacitance	Cout		185		pF	V∟=0, f=1MHz
Transmis	Turn-On Time	Ton		1.5	5	ms	l⊧=5mA, l∟=100mA,
sion	Turn-Off Time	Toff		0.05	2	ms	
Coupled	I/O Isolation Resistance	Rı/o	5			GΩ	DC500V
	I/O Capacitance	Ci/o		0.8	1.5	pF	f=1MHz

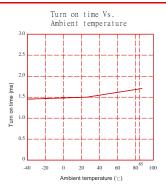
Please obey the following conditions to ensure proper device operation and resetting. Input LED current (Recommended value): IF ≥5mA and ≤30mA

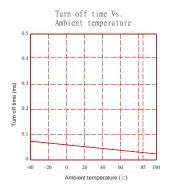
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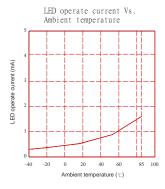
Engineering Data

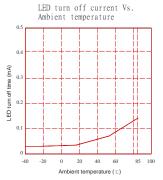




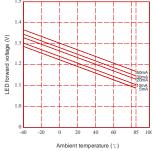




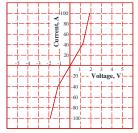




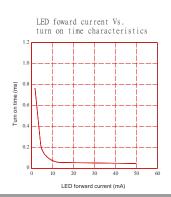
LED forward voltage Vs. Ambient temperature



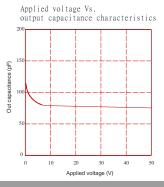
Voltage Vs. currennt characteristics of output at MOS portion



Off state leakage current Vs. Load voltage characteristics



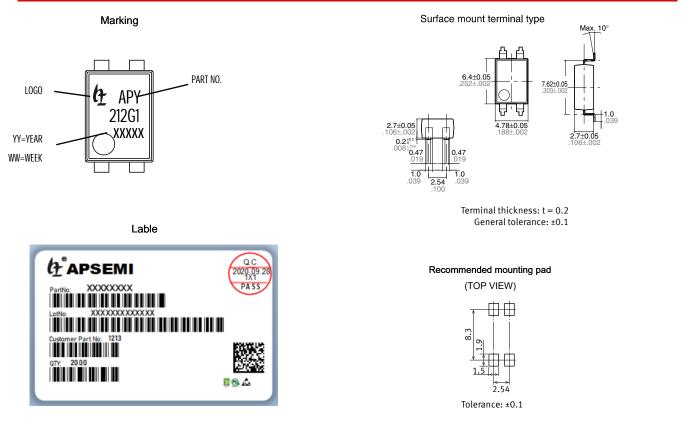
LED foward current Vs. turn off time characteristics



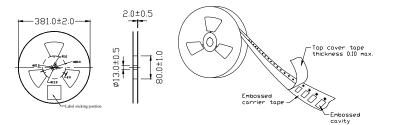
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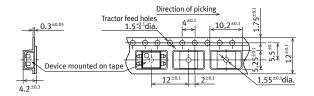


Dimensions and SMD-4 Package Unit: mm



Tape dimensions (tape reel)

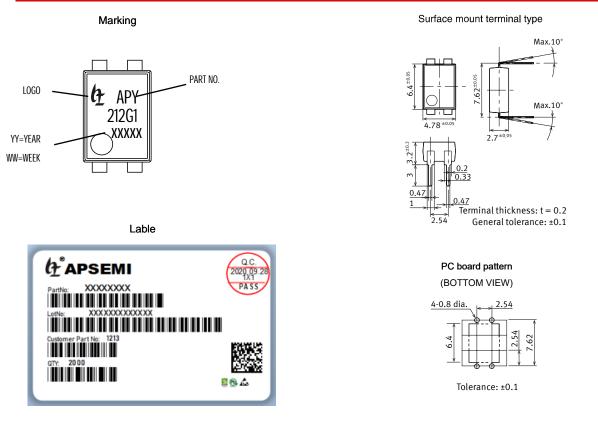




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Dimensions and DIP-4 Package Unit: mm



Tape dimensions (tape reel)

DIP type

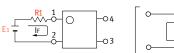
Devices are packaged in a tube so that pin No. 1 is on the stopper B side. Observe correct orientation when mounting them on PC boards.

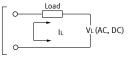




Using Methods

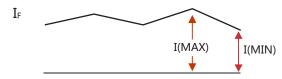
Examples of resistance value to control LED forward current (IF=5mA)





E1	R1 (Approx)
3.3V	300 Ω
5.0V	600 Ω
12V	1.9KΩ
24V	4.1K Ω

LED forward current must be more than 5mA , at I(MIN) ,and less than 30mA , at I(MAX).



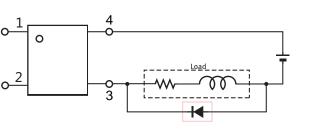
Recommended Operating Conditions

Please obey the following conditions to ensure proper device operation and resetting. Input LED current (Recommended value):

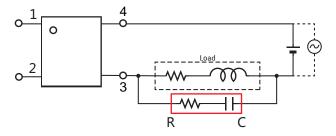
Characteristic	Symbol	Min	Тур.	Max	Unit
Forward current	١ _F	5.0	7.0	30	mA

Protection Circuit

Clamp diode is connected in parallel with the load. Absorb capacity with external diode.



CR Snubber is connected in parallel with the load. Absorb capacity with buffer capacity.



When adding diodes, buffer circuits (C-R), and other protections, they need to be installed near the MOS RELAY to be effective. Adding protection elements may result in a slow reset time, so adjust them according to the actual situation before use.

Note: When developing designs using this product, perform the expected performance of the equipment under the operating conditions recommended by the guidelines in this document. Continuous use under heavy loads (including, but not limited to, the application of high temperatures/current/voltage and significant changes in temperature, etc.) may result in deterioration of the reliability of this product.

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